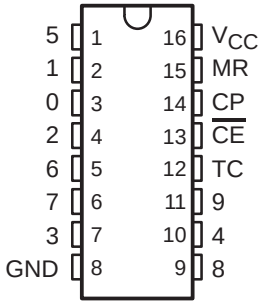
- **4.5-V to 5.5-V Operation**
- **Fully Static Operation**
- **Buffered Inputs**
- **Common Reset**
- **Positive-Edge Clocking**
- **Balanced Propagation Delay and Transition Times**
- **Direct LSTTL Input Logic Compatibility**
  **– $V_{IL}$ = 0.8 V Maximum; $V_{IH}$ = 2 V Minimum**
- **CMOS Input Compatibility**
  **– $I_I \leq 1\ \mu A$ at $V_{OL}$, $V_{OH}$**
- **Packaged in Ceramic (F) DIP Packages and Also Available in Chip Form (H)**

**F PACKAGE**
**(TOP VIEW)**




## description

The CD54HCT4017 is a high-speed silicon-gate CMOS 5-stage Johnson counter with ten decoded outputs. Each decoded output normally is low and sequentially goes high on the low-to-high transition of the clock (CP) input. Each output stays high for one clock period of the ten-clock-period cycle. The terminal count (TC) output transitions low to high after output ten (9) goes low, and can be used in conjunction with the clock enable ($\overline{CE}$) input to cascade several stages. $\overline{CE}$ disables counting when in the high state. The master reset (MR) input, when taken high, sets all the decoded outputs, except 0, to low.

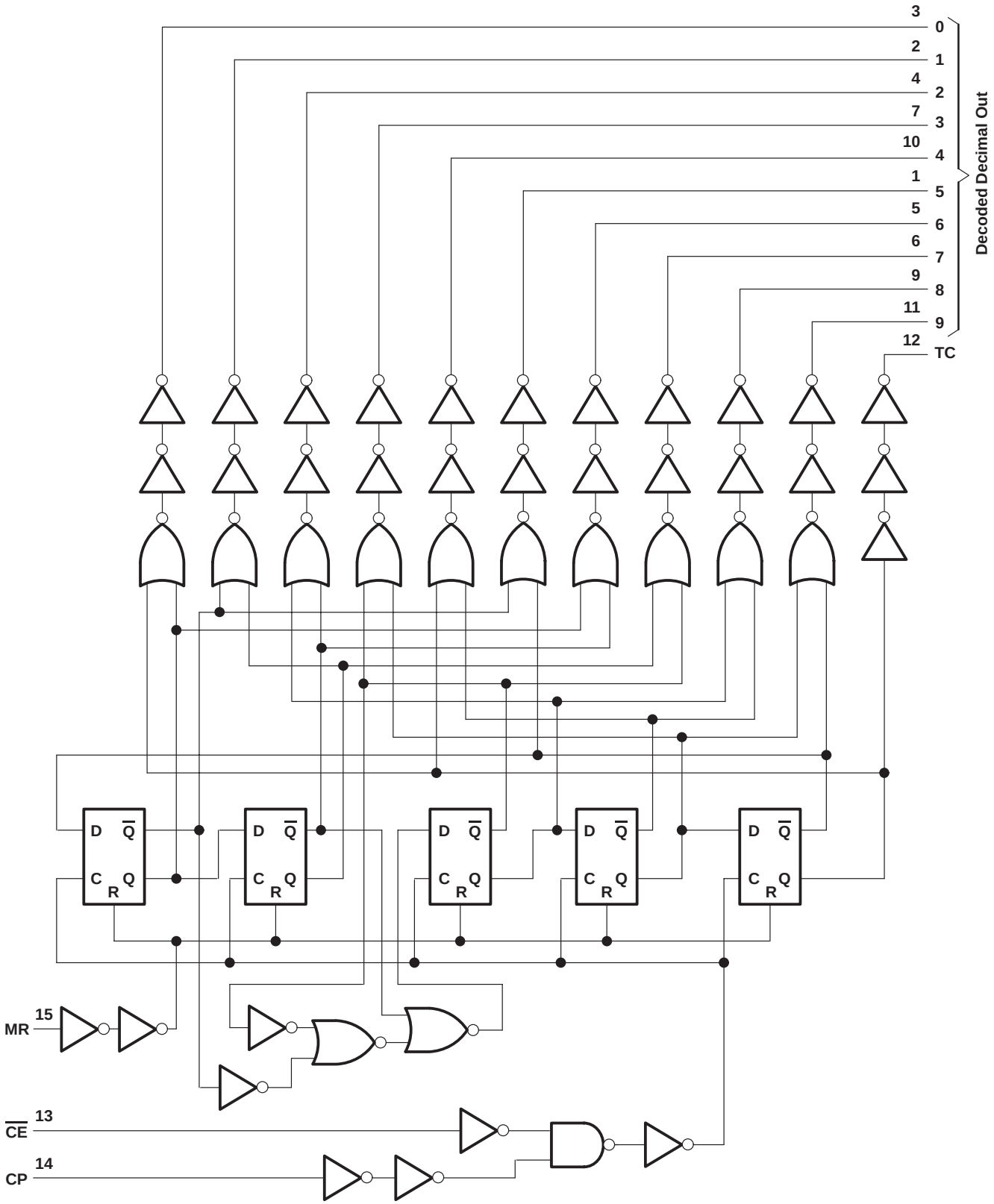
The CD54HCT4017 is characterized for operation over the full military temperature range of –55°C to 125°C.

**FUNCTION TABLE**

| INPUTS | | | OUTPUT STATE† |
|---|---|---|---|
| CP | $\overline{CE}$ | MR | |
| L | X | L | No change |
| X | H | L | No change |
| X | X | H | 0 = H<br>1–9 = L |
| ↑ | L | L | Increments counter |
| ↓ | X | L | No change |
| X | ↑ | L | No change |
| H | ↓ | L | Increments counter |

† If n < 5, TC = H; otherwise, TC = L.

## logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, $V_{CC}$ . . . . . –0.5 V to 7 V
Input clamp current, $I_{IK}$ ($V_I < 0$ V or $V_I > V_{CC}$) . . . . . ±20 mA
Output clamp current, $I_{OK}$ ($V_O < 0$ V or $V_O > V_{CC}$) . . . . . ±20 mA
Continuous output current, each output pin, $I_O$ ($V_O > 0$ V or $V_O < V_{CC}$) . . . . . ±25 mA
$V_{CC}$ or ground current, $I_{CC}$ . . . . . ±50 mA
Storage temperature range, $T_{stg}$ . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 1)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage | | 4.5 | 5.5 | V |
| $V_{IH}$ | High-level input voltage | $V_{CC}$ = 4.5 V to 5.5 V | 2 | | V |
| $V_{IL}$ | Low-level input voltage | $V_{CC}$ = 4.5 V to 5.5 V | | 0.8 | V |
| $V_I$ | Input voltage | | 0 | $V_{CC}$ | V |
| $V_O$ | Output voltage | | 0 | $V_{CC}$ | V |
| $t_t$ | Input transition (rise and fall) time | $V_{CC}$ = 2 V | 0 | 1000 | ns |
| | | $V_{CC}$ = 4.5 V | 0 | 500 | |
| | | $V_{CC}$ = 6 V | 0 | 400 | |
| $T_A$ | Operating free-air temperature | | –55 | 125 | °C |

NOTE 1: All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | $V_{CC}$ | $T_A$ = 25°C | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | | | |
| $V_{OH}$ | CMOS loads | $V_I = V_{IH}$ or $V_{IL}$, $I_O$ = –0.02 mA | 4.5 V | 4.4 | | | 4.4 | | V |
| | TTL loads | $V_I = V_{IH}$ or $V_{IL}$, $I_O$ = –4 mA | 4.5 V | 3.98 | | | 3.7 | | |
| $V_{OL}$ | CMOS loads | $V_I = V_{IH}$ or $V_{IL}$, $I_O$ = 0.02 mA | 4.5 V | | | 0.1 | | 0.1 | V |
| | TTL loads | $V_I = V_{IH}$ or $V_{IL}$, $I_O$ = 4 mA | 4.5 V | | | 0.26 | | 0.4 | |
| $I_I$ | | $V_I = V_{CC}$ to 0 | 5.5 V | | | ±100 | | ±1000 | nA |
| $I_{CC}$ | | $V_I = V_{CC}$ or 0 | 5.5 V | | | 8 | | 160 | µA |
| $\Delta I_{CC}$† | | $V_I = V_{CC}$ to 2.1 V, $I_O$ = 0 | 4.5 to 5.5 V | | 100 | 360 | | 490 | µA |
| $C_i$ | | | | | | 10 | | 10 | pF |

† For dual-supply systems, theoretical worst case ($V_I$ = 2.4 V, $V_{CC}$ = 5.5 V) specification is 1.8 mA.

**INPUT LOADING**

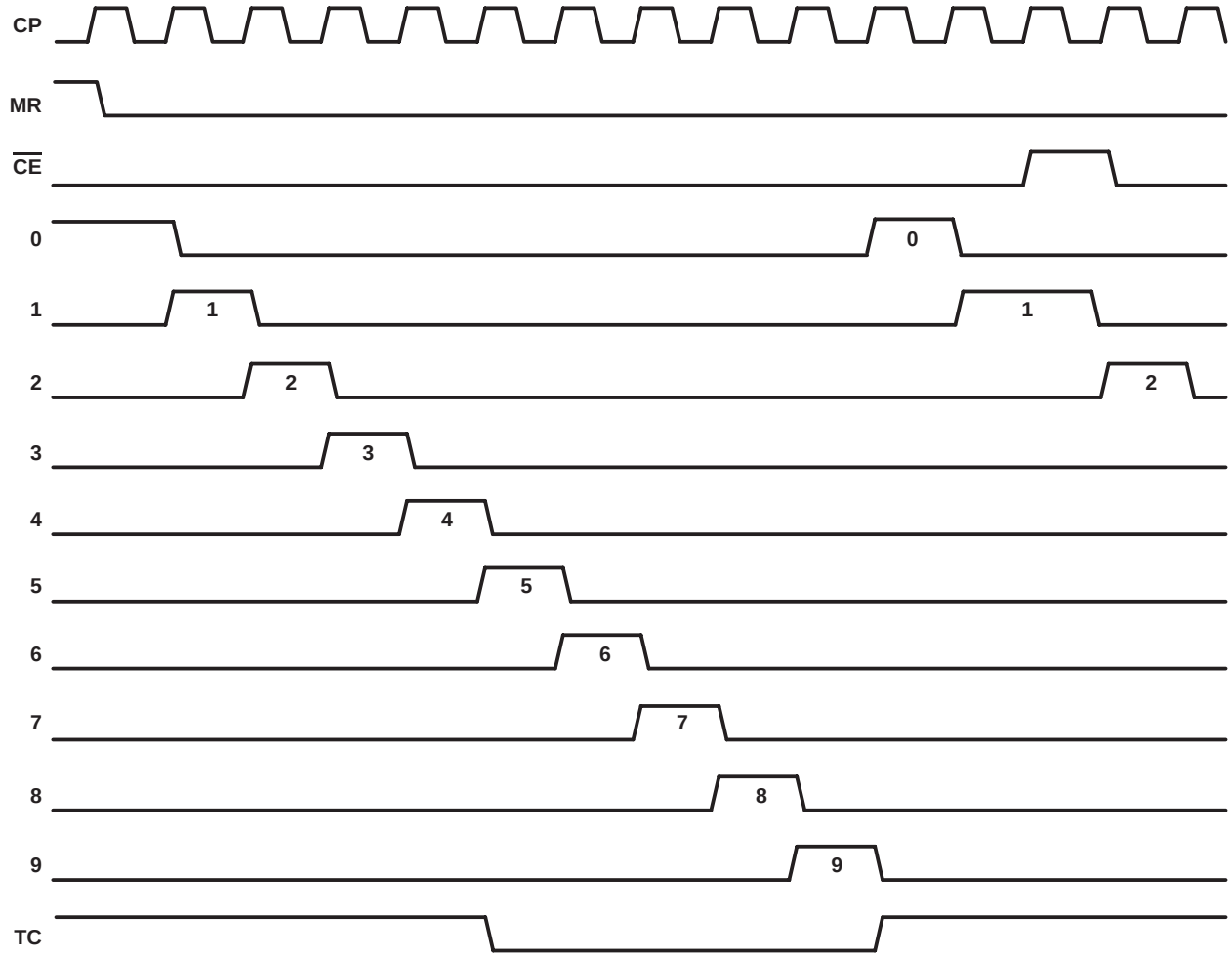
| INPUT | UNIT LOAD |
|---|---|
| CP | 0.15 |
| $\overline{CE}$ | 0.25 |
| MR | 0.3 |

Unit load is $\Delta I_{CC}$ limit, e.g., 360 µA MAX at $T_A$ = 25°C.

## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | | $V_{CC}$ | $T_A$ = 25°C | | MIN | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | | | MIN | MAX | | | |
| $f_{clock}$ | Maximum clock frequency | | 4.5 V | | 25 | | 17 | MHz |
| $t_w$ | Pulse duration | CP | 4.5 V | | 16 | | 24 | ns |
| | | MR | 4.5 V | | 16 | | 24 | |
| $t_{su}$ | Setup time, $\overline{CE}$ to CP | | 4.5 V | 15 | | 22 | | ns |
| $t_h$ | Hold time, $\overline{CE}$ to CP | | 4.5 V | 0 | | 0 | | ns |
| $t_{rem}$ | Removal time, MR | | 4.5 V | 5 | | 5 | | ns |

## timing requirements



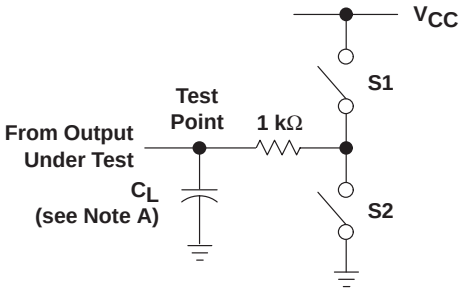
## switching characteristics, $C_L$ = 50 pF, $T_A$ = 25°C (see Figures 1 and 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ | $T_A$ = 25°C | | $T_A$ = –55°C TO 125°C | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | | | MIN | MAX | MIN | MAX | |
| $f_{max}$ | | | 4.5 V | 25 | | 17 | | MHz |
| $t_{PLH}$ | CP | Any output | 4.5 V | | 46 | | 69 | ns |
| $t_{PHL}$ | | TC | | | 46 | | 69 | |
| $t_{PLH}$ | $\overline{CE}$ | Any output | 4.5 V | | 50 | | 75 | ns |
| $t_{PHL}$ | | TC | | | 50 | | 75 | |
| $t_{PLH}$ | MR | Any output | 4.5 V | | 46 | | 69 | ns |
| $t_{PHL}$ | | TC | | | 46 | | 69 | |
| $t_{THL}$ | | Any output | 4.5 V | | 15 | | 22 | ns |
| $t_{TLH}$ | | TC | | | 15 | | 22 | |

## operating characteristics

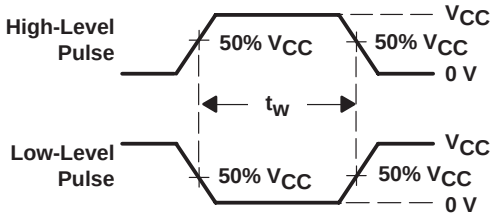
| PARAMETER | | TEST CONDITIONS | TYP | UNIT |
|---|---|---|---|---|
| $C_{pd}$ | Power dissipation capacitance | No load | 39 | pF |

## PARAMETER MEASUREMENT INFORMATION

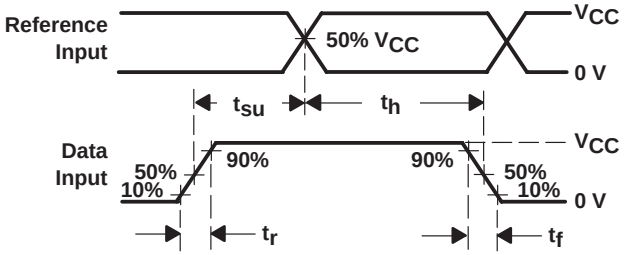



LOAD CIRCUIT

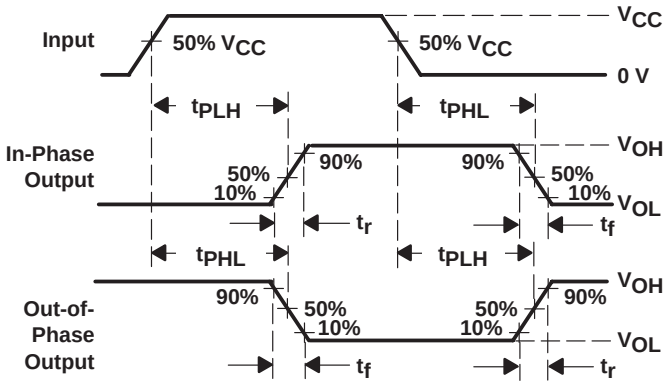
| PARAMETER | | S1 | S2 |
|---|---|---|---|
| $t_{en}$ | $t_{PZH}$ | Open | Closed |
| | $t_{PZL}$ | Closed | Open |
| $t_{dis}$ | $t_{PHZ}$ | Open | Closed |
| | $t_{PLZ}$ | Closed | Open |
| $t_{pd}$ or $t_t$ | | Open | Open |



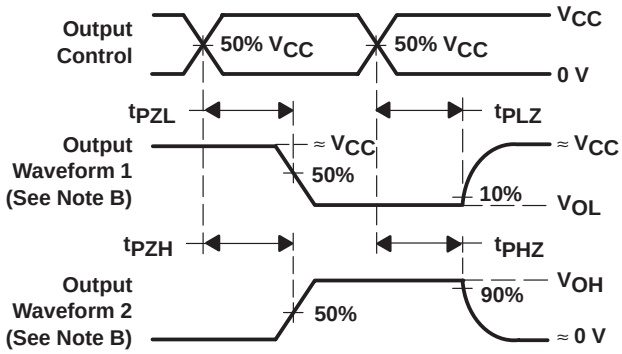

VOLTAGE WAVEFORMS
PULSE DURATIONS




VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. $C_L$ includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O$ = 50 Ω, $t_r$ = 6 ns, $t_f$ = 6 ns.
D. The outputs are measured one at a time with one input transition per measurement.
E. $t_{PLZ}$ and $t_{PHZ}$ are the same as $t_{dis}$.
F. $t_{PZL}$ and $t_{PZH}$ are the same as $t_{en}$.
G. $t_{PLH}$ and $t_{PHL}$ are the same as $t_{pd}$.

**Figure 1. Load Circuit and Voltage Waveforms**

## PARAMETER MEASUREMENT INFORMATION

| INPUT LEVEL | $V_{CC}$ |
|---|---|
| $V_S$ | 0.5 $V_{CC}$ |

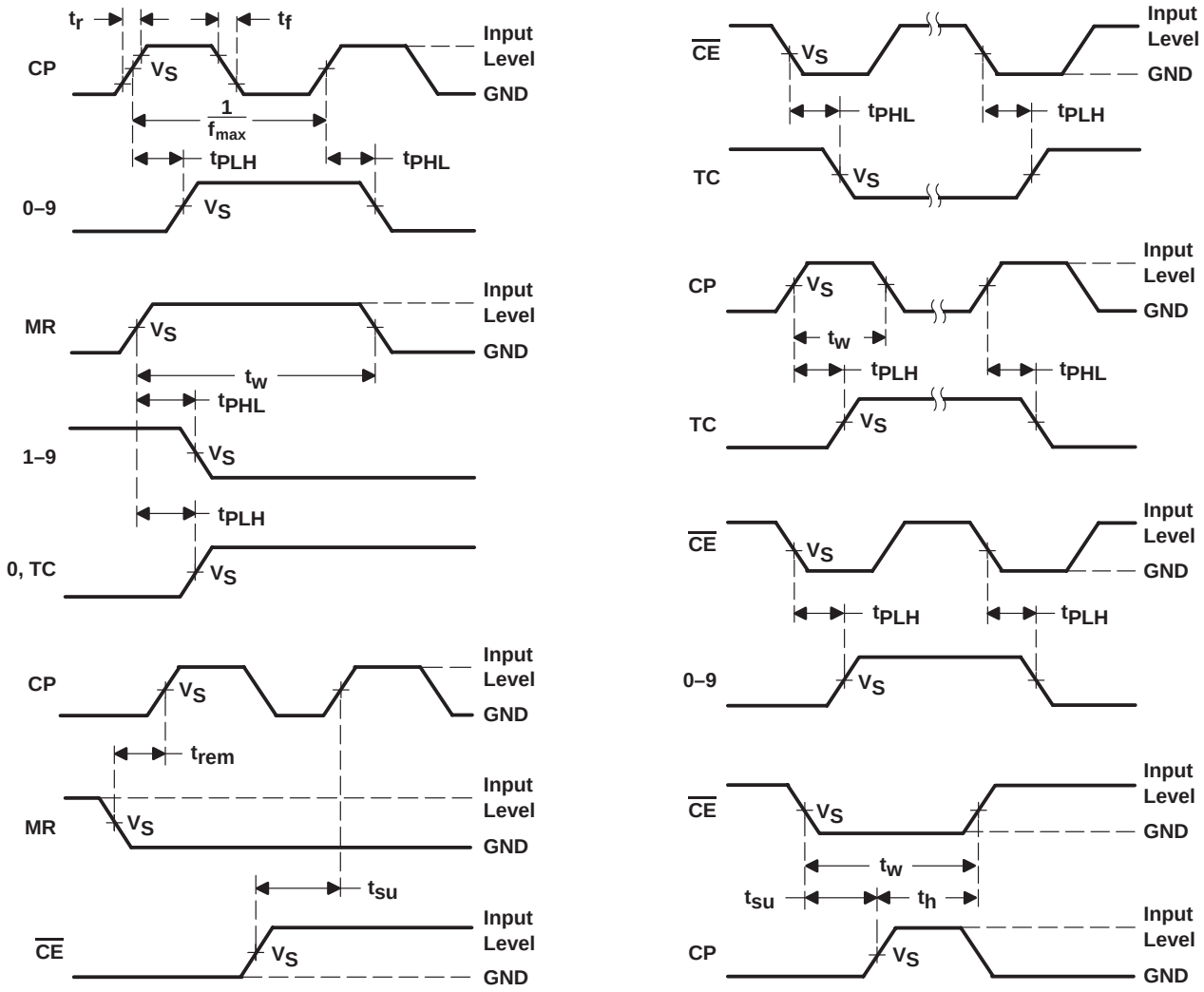



**Figure 2. Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) |
|---|---|---|---|---|---|---|---|---|
| CD54HCT4017F3A | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

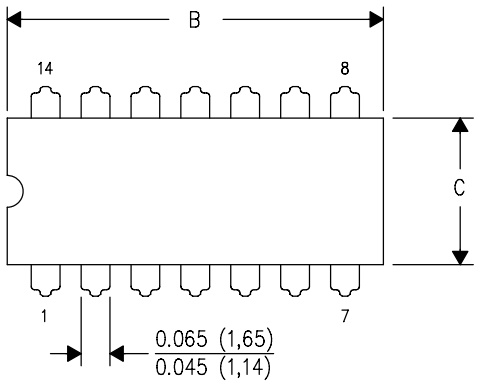
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

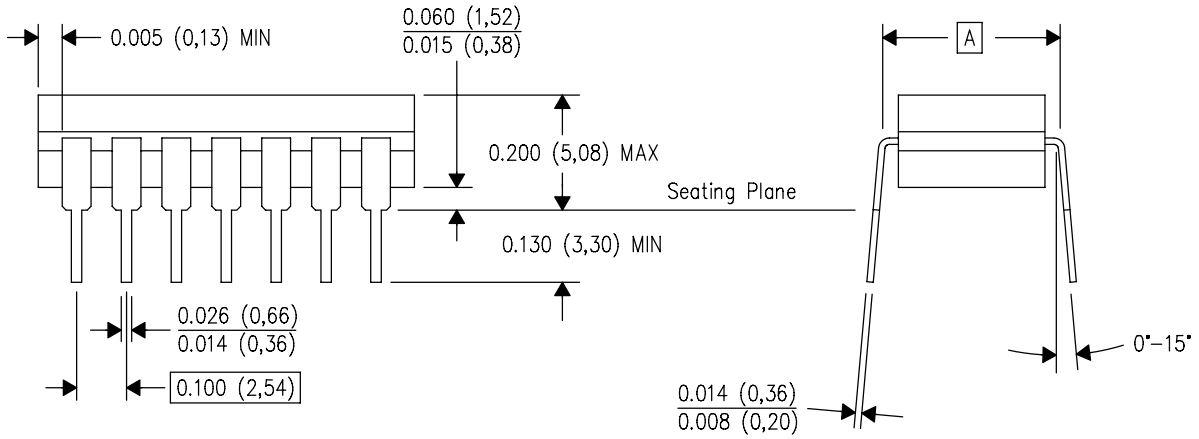
J (R–GDIP–T**)

14 LEADS SHOWN

# CERAMIC DUAL IN–LINE PACKAGE




| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |




4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

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